



Art 1765  
2A/A

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of:  
Chin et al.

Confirmation Number: 8566

Serial No.: 09/310,256

Group Art Unit: 1765

Examiner: Ahmed, S.

Filed: May 12, 1999

TKHR Docket No. 252016-2270

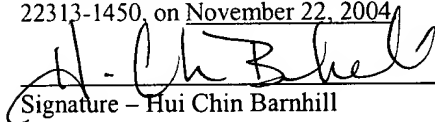
For: METHOD TO REDUCE PARTICLE  
LEVEL FOR DRY ETCH

Top-Team Ref. 0503-A30690US

TSMC Ref. TSMC98-574

**Certificate of Mailing**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Mail Stop Amendment; Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 22, 2004.

  
Signature - Hui Chin Barnhill

**AMENDMENT AND RESPONSE TO NOTICE OF NON-COMPLIANCE**

Mail Stop - Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is in response to a Note of Non-Compliance of 07/24/03. Please consider the following:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 10 of this paper.